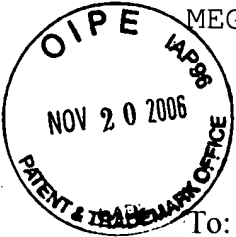


ITJ



MEG03-005

appl. no. 10/796,427

Nov. 15, 2006

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/796,427	03/09/04
MOU-SHIUNG LIN		
"WIREBOND PAD FOR SEMICONDUCTOR CHIP OR WAFER"		
Grp. Art Unit: 2822	LEWIS, MONICA	

#### RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action mailed Aug. 15, 2006, please consider the remarks as follows:

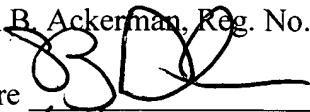
#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Nov. 15, 2006.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

  
11/15/06

Amendments to the Claims begin on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.